



Purpose

Eon Silicon Solution Inc. (hereinafter called "Eon") is going to provide its products' top marking on ICs with < cFeon > from January 1st, 2009, and without any change of the part number and the compositions of the ICs. Eon is still keeping the promise of quality for all the products with the same as that of Eon delivered before. Please be advised with the change and appreciate your kindly cooperation and fully support Eon's product family.

Eon products' Top Marking

cFeon Top Marking Example:

cFeon

Part Number: XXXX-XXX

Lot Number: XXXXX

Date Code: XXXXX

For More Information

Please contact your local sales office for additional information about Eon memory solutions.



EN71GL064 Base MCP

**Stacked Multi-Chip Product (MCP) Flash Memory and RAM
64 Megabit (4M x 16-bit) CMOS 3.0 Volt-only Page Mode Flash
Memory and 32 Megabit (2M x 16-bit) Pseudo Static RAM**

Distinctive Characteristics

MCP Features

- Power supply voltage of 2.7 V to 3.3V
- High performance
 - 70 ns
- Package
 - 7 x 9 x 1.2mm 56 ball FBGA
- Operating Temperature
 - 25°C to +85°C

General Description

The EN71GL series is a product line of stacked Multi-Chip Product (MCP) packages and consists of:

- EN29GL064AT Flash memory with Top Boot Sector.
- Pseudo SRAM.

For detailed specifications, please refer to the individual datasheets listed in the following table.

| Device | Document |
|-------------|-------------|
| NOR Flash | EN29GL064AT |
| Pseudo SRAM | ENPSL32 |

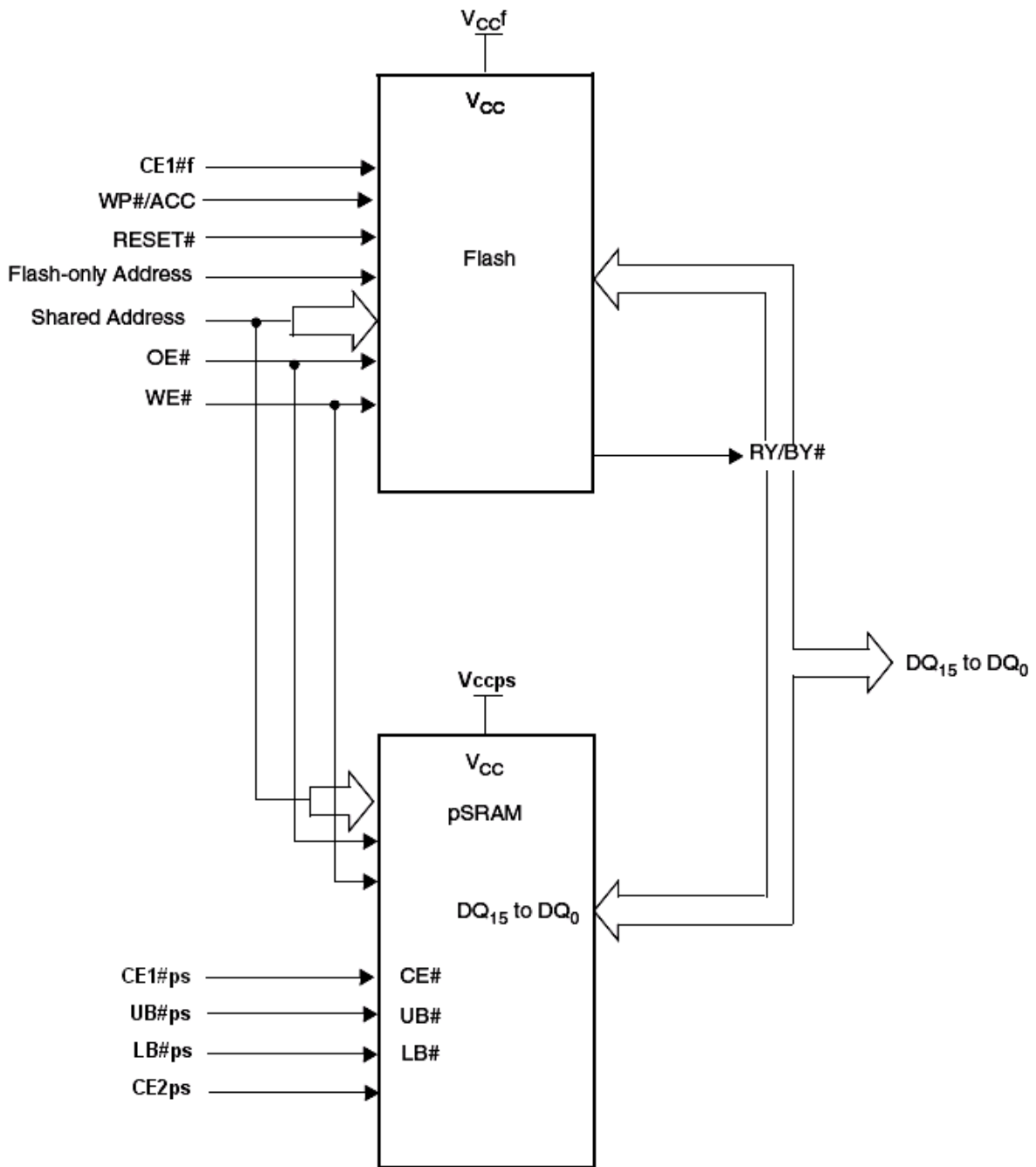
Product Selector Guide

64Mb Flash Memory

| | | | |
|-----------------------|-------------|-----------------------------|-----------|
| Device-Model# | EN71GL064B0 | pSRAM density | 32M pSRAM |
| Flash Access time | 70ns | pSRAM Access time | 70ns |
| Page read Access time | 25ns | pSRAM Page read Access time | 25ns |
| Package | 56 FBGA | | |

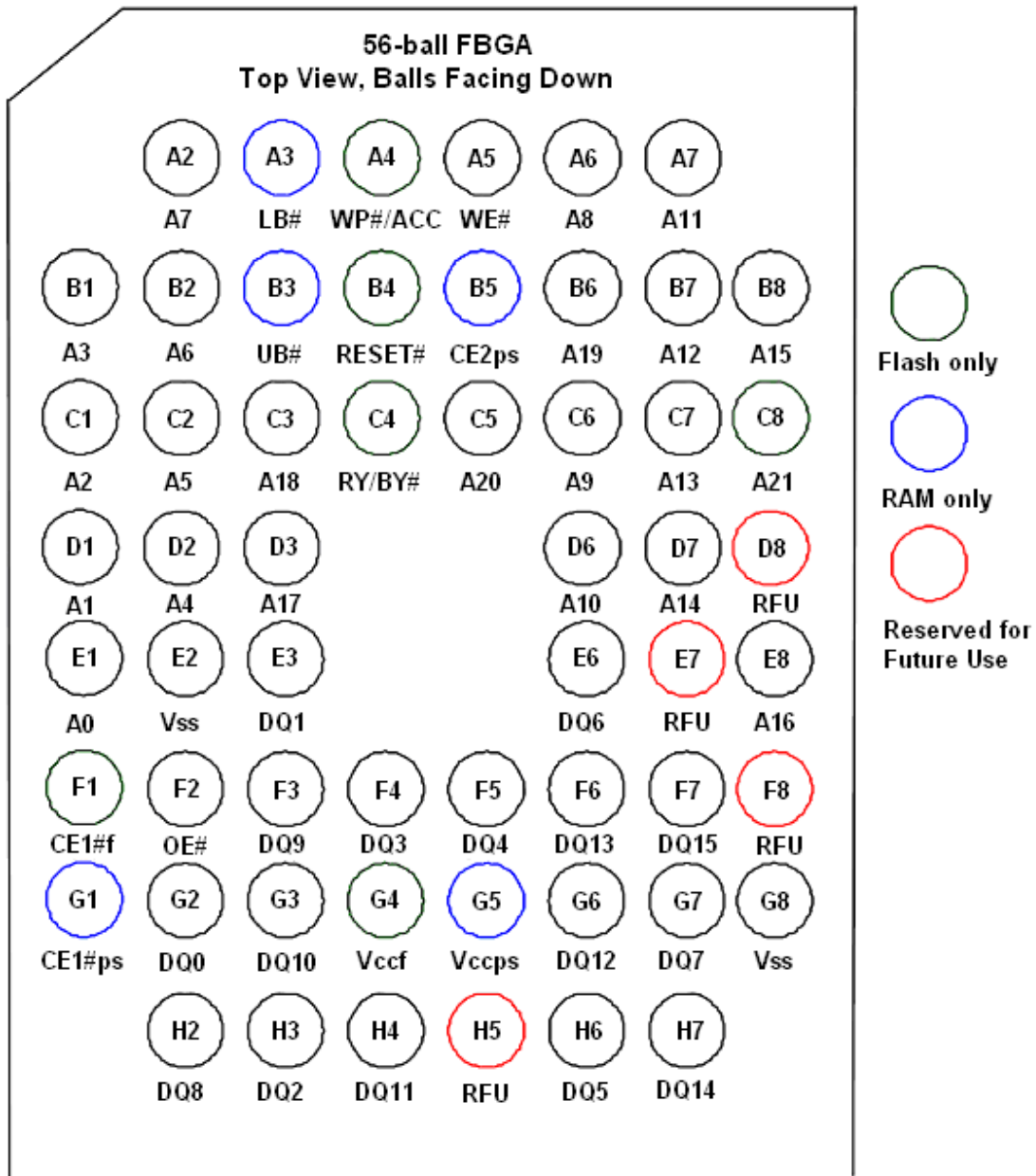


MCP Block Diagram





Connection Diagram

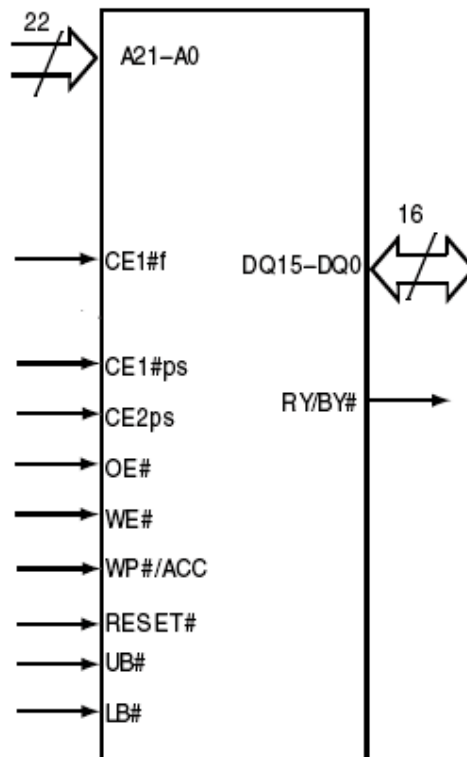


| MCP | Flash-only Addresses | Shared Addresses |
|-------------|----------------------|------------------|
| EN71GL064B0 | A21 | A20 – A0 |

Pin Description

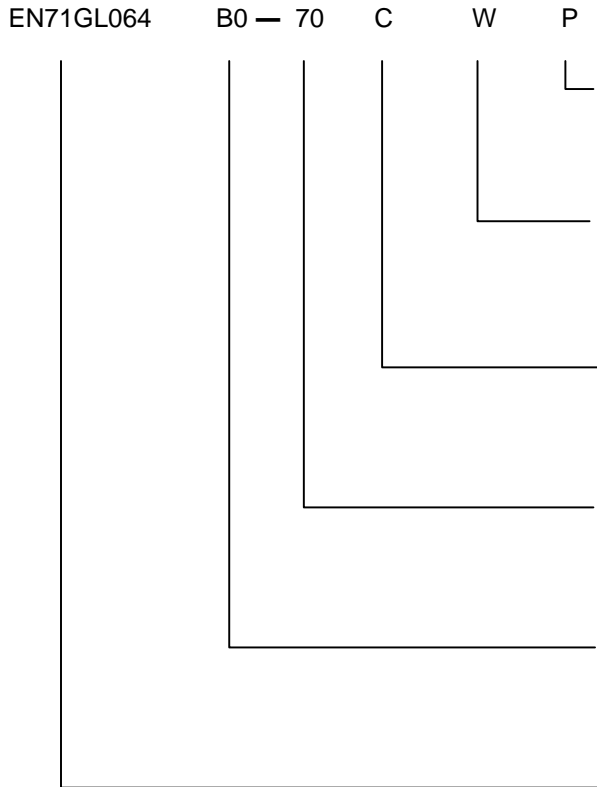
| Signal | Description |
|-------------------|---|
| A21–A0 | 22 Address Inputs (Common) |
| DQ15–DQ0 | 16 Data Inputs/Outputs (Common) |
| CE1#f | Chip Enable 1 (Flash) |
| CE1#ps | Chip Enable 1 (pSRAM) |
| CE2ps | Chip Enable 2 (pSRAM) |
| OE# | Output Enable (Common) |
| WE# | Write Enable (Common) |
| RY/BY# | Ready/Busy Output (Flash) |
| UB# | Upper Byte Control (pSRAM) |
| LB# | Lower Byte Control (pSRAM) |
| RESET# | Hardware Reset Pin, Active Low (Flash) |
| WP#/ACC | Hardware Write Protect/Acceleration Pin (Flash) |
| V _{ccf} | Flash 3.0 volt-only single power supply |
| V _{ccps} | pSRAM Power Supply |
| V _{ss} | Device Ground (Common) |
| NC | Pin Not Connected Internally |

Logic Symbol





ORDERING INFORMATION



PACKAGING CONTENT

P = Pb Free

TEMPERATURE RANGE

W = Wireless (-25°C to +85°C)

PACKAGE

C =56-Ball Fine Pitch Ball Grid Array (FBGA)
0.80mm pitch, 7mm x 9mm package

SPEED

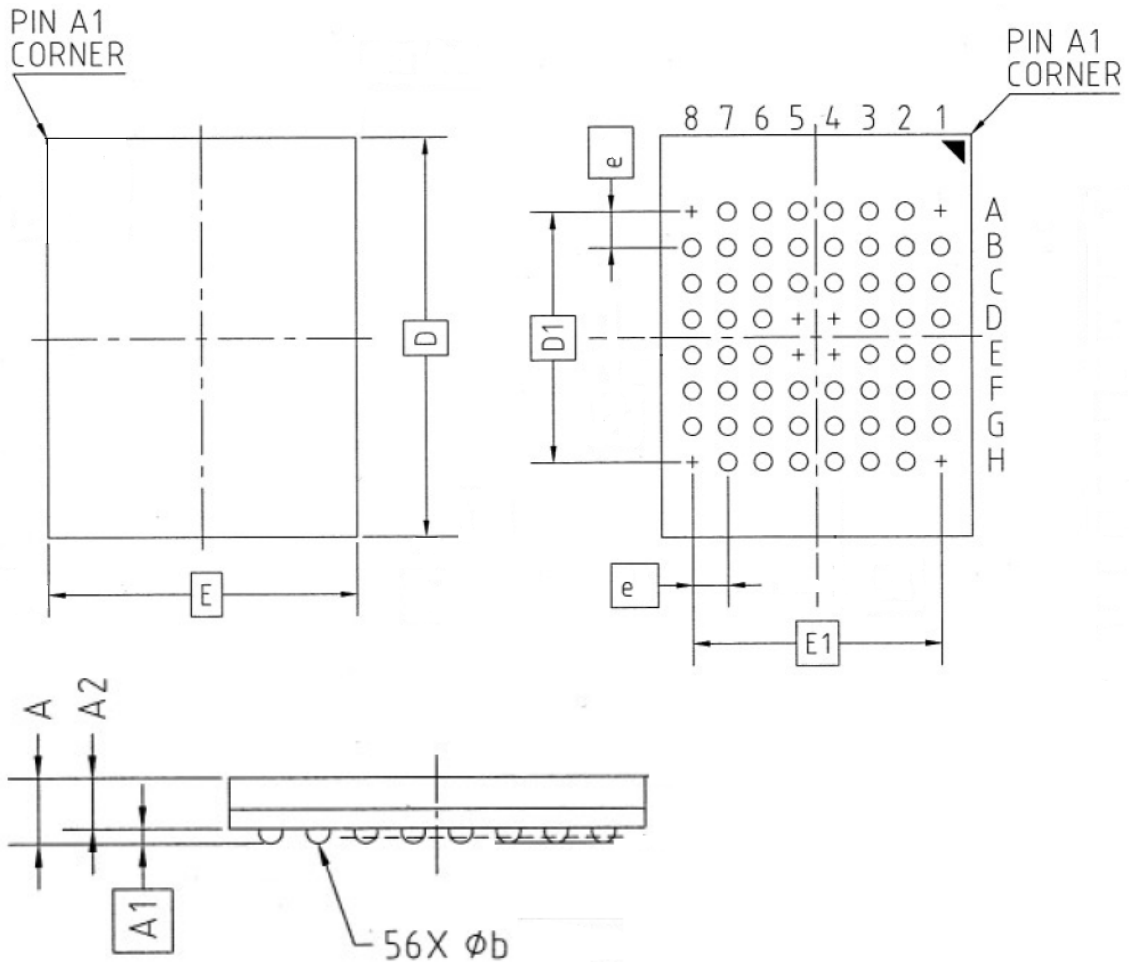
70 = 70ns

pSRAM density

B0 = 32M pSRAM

BASE PART NUMBER

EN = Eon Silicon Solution Inc.
71GL = Multi-chip Product (MCP)
3.0V Page Mode Flash Memory and RAM
064 = 64 Megabit (4M x 16)

PACKAGE MECHANICAL
**56-ball Fine-Pitch Ball Grid Array (FBGA) 7 x 9 mm Package,
pitch: 0.8mm, ball: 0.4mm**


| SYMBOL | DIMENSION IN MM | | |
|--------|-----------------|------|------|
| | MIN. | NOR | MAX |
| A | --- | --- | 1.20 |
| A1 | 0.25 | 0.30 | 0.35 |
| A2 | 0.80 | --- | 0.95 |
| D | 8.95 | 9.00 | 9.05 |
| E | 6.95 | 7.00 | 7.05 |
| D1 | --- | 5.60 | --- |
| E1 | --- | 5.60 | --- |
| e | --- | 0.80 | --- |
| b | 0.35 | 0.40 | 0.45 |

Note : Controlling dimensions are in millimeters (mm).



Revisions List

| Revision No | Description | Date |
|--------------------|---|-------------|
| A | Initial Release | 2009/10/20 |
| B | Update EN29GL064 (Page mode) Flash memory with Top Boot Sector on page 2. | 2009/11/23 |
| C | Update the NOR Flash from EN29GL064 to EN29GL064AT. | 2012/05/21 |